



TopFlex

Distributed by:



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ThinFlex-Q2,Q-2010TA-mb Halogen Free Coverlay

ThinFlex-Q2 is polyimide film coated on one side with modified halogen free epoxy adhesive. Coverlay can be used in the fabrication of flexible printed circuits for circuit protection and insulation.

1. Product Characteristics:

- * Excellent heat resistance
- * Good dimensional stability
- * Excellent anti-flammability (UL 94V-0; UL File No. E219724)
- * Excellent chemical resistance
- * Excellent thermal, mechanical and electrical properties
- * Products can meet the environmental requirements of RoHs/Reach....

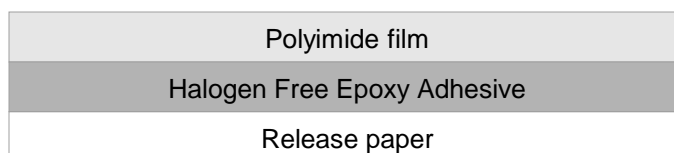
2. Specifications:

[Q] - [20 | 10 | T | A] - [mb]

Product	PI Thickness	Adhesive Thickness	PI Film	Release Paper	Adhesive
Q :Coverlay	20:2.0mil	10:1.0mil	TAIMIDE	Release Paper	mb
Supply Size	W:250/500 ±1mm;L:200 +2/-0m (Roll type)				

*Other thicknesses and dimensions are available on customers' demand.

3. Constructions:





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4. Properties:

Test Item	Unit	Q-2010TA - mb	Test Method
Peel Strength			
As received	kgf/cm	≥ 0.7	IPC-TM650 2.4.9
Solder float	kgf/cm	≥ 0.7	IPC-TM650 2.4.9
Solder float	PASS	288°C 10sec	IPC-TM650 2.4.13
Surface Resistance	Ω	$\geq 1.0 \times 10^{10}$	IPC-TM650 2.5.17
Volume Resistance	Ω -cm	$\geq 1.0 \times 10^{12}$	IPC-TM650 2.5.17
Dielectric Constant	-	3.5	ASTM D150
Dissipation Factor	-	0.026	
Resin Flow	um	80~150	ThinFlex
Dimensional Stability			
MD	%	-0.2~0.2	IPC-TM-650 2.2.4
TD	%	-0.2~0.2	IPC-TM-650 2.2.4
Thickness Tolerance	%	$\pm 10\%$	ThinFlex
ULFlame Class	-	94V-0	UL

* Above data are typical values, and are not guaranteed values.



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5. Lamination and Process Conditions

ThinFlex Halogen Free Coverlay are typically used in the following ranges:

A) Traditional Hot Press Conditions:

1. Part Temperature: $170 \pm 10^{\circ}\text{C}$
2. Pressure: $30 \pm 5 \text{ kg/cm}^2$
3. Time: $\geq 60 \text{ min}$, at holding time

B) Fast Hot Press Condition:

1. Pre-Press Temp / Time / Pressure: $180 \pm 10^{\circ}\text{C}$ / 10sec / 0 kg/cm²
2. Hot-Press Temp / Time / Pressure: $180 \pm 10^{\circ}\text{C}$ / 120sec / $100 \pm 20 \text{ kg/cm}^2$
3. Post Cure Condition: 160°C / 60-120 minutes

6. Storage:

ThinFlex-Q2 will meet its shelf-life for at least 3 months from product date and stored in the original packaging in a dry place at temperatures below $4 \pm 2^{\circ}\text{C}$; $50 \pm 20\%$ RH.

7. Back to the temperature parameter :

Time : At least 2 hours

Temperature : $20 \pm 10^{\circ}\text{C}$

Humidity : $50 \pm 20\%$

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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